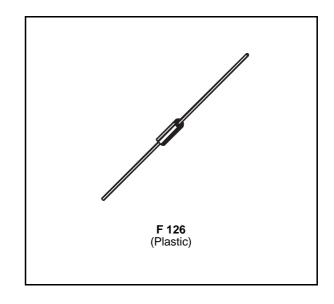


HIGH EFFICIENCY FAST RECOVERY RECTIFIER DIODES

- VERY LOW CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD AND REVERSE RECOVERY TIMES
- HIGH SURGE CURRENT
- THE SPECIFICATIONS AND CURVES ENABLE THE DETERMINATION OF t_{rr} AND I_{RM} AT 100°C UNDER USERS CONDITIONS



DESCRIPTION

Low voltage drop and rectifier suited for switching mode base drive and transistor circuits.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
I _{FRM}	Repetive peak forward current	$t_p \le 20 \mu s$	50	Α
I _{F (AV)}	Average forward current* $ T_{a=} 90^{\circ}C $ $ \delta = 0.5 $		1.5	А
I _{FSM}	Surge non repetitive forward current $t_p = 10 ms$ Sinusoidal		50	А
P _{tot}	Power dissipation* $T_{a=}90^{\circ}C$		1.3	W
$T_{stg} \ T_{j}$	Storage and junction temperature range	- 40 to + 150 - 40 to + 150	°C	
TL	Maximum lead temperature for soldering during case	230	°C	

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive peak reverse voltage	200	V
V _{RSM}	Non repetitive peak reverse voltage	220	V

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
R _{th (j - a)}	Junction-ambient*	45	°C/W

^{*} On infinite heatsink with 10mm lead length.

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ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Synbol	Test Conditions			Тур.	Max.	Unit
I _R	T _j = 25°C	$V_R = V_{RRM}$			10	μΑ
	T _j = 100°C				0.5	mA
V _F	T _j = 25°C	I _F = 4.5A			1.2	V
	T _j = 100°C	I _F = 1.5A			0.85	

RECOVERY CHARACTERISTICS

Symbol	Test Conditions				Тур.	Max.	Unit
t _{rr}	$T_j = 25^{\circ}C$ $V_R = 30V$	I _F = 1A See figure 10	$di_F/dt = -50A/\mu s$			35	ns
Q _{rr}	$T_j = 25^{\circ}C$ $V_R \leq 30V$	I _F = 1A	$di_F/dt = -20A/\mu s$		10		nC
t _{fr}	T _j = 25°C Measured at 1.1 x V _F	I _F = 1A	t _r = 10ns		30		ns
V _{FP}	T _j = 25°C	I _F = 1A	t _r = 10ns		5		V

To evaluate the conduction losses use the following equations:

 $V_F = 0.66 + 0.075 I_F$ $P = 0.06 \times I_{F(AV)} + 0.075 I_F^2_{(RMS)}$

Figure 1. Maximum average power dissipation versus average forward current.

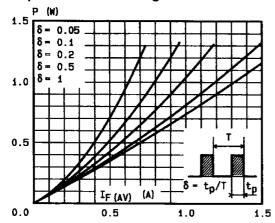


Figure 3. Thermal resistance versus lead Mounting n°1

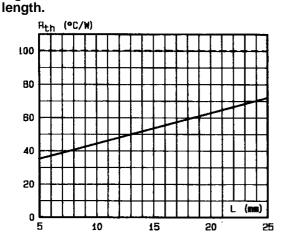


Figure 4. Transient thermal impedance junction-ambient for mounting n^2 versus pulse duration (L = 10 mm).

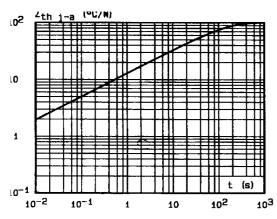
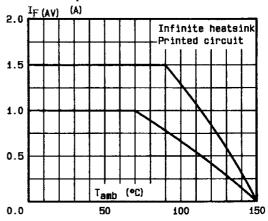


Figure 2. Average forward current versus ambient temperature.



Mounting n°1
INFINITE HEATSINK

Mounting n°2 PRINTED CIRCUIT

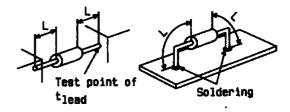


Figure 5. Peak forward current versus peak forward voltage drop (maximum values).

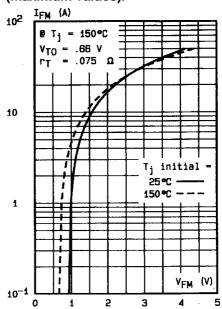


Figure 6. Capacitance versus reverse voltage applied.

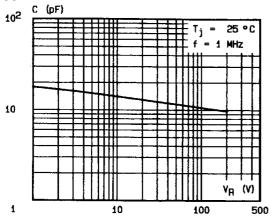


Figure 7. Recovery time versus di_F/dt.

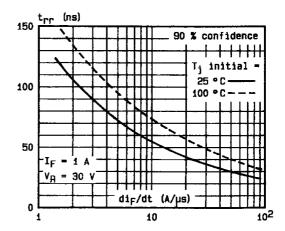


Figure 8. Peak reverse current versus di_F/dt.

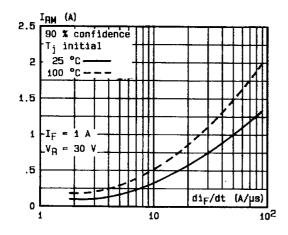


Figure 9. Dynamic parameters versus junction temperature.

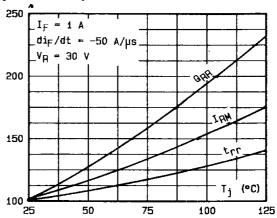
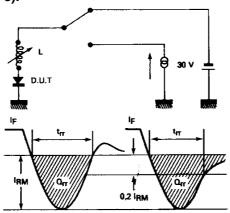


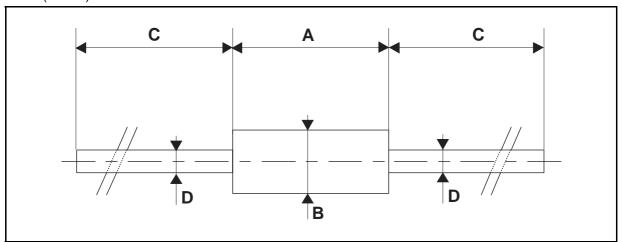
Figure 10. Measurement of t_{rr} (Fig. 7) and I_{RM} (Fig. 8).



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PACKAGE MECHANICAL DATA

F 126 (Plastic)



		DIMENSIONS					
	REF.	Millimeters			Inches		
		Min.	Тур.	Max.	Min.	Тур.	Max.
	Α	6.05	6.20	6.35	0.238	0.244	0.250
	В	2.95	3.00	3.05	0.116	0.118	0.120
	C	26		31	1.024		1.220
	D	0.76	0.81	0.86	0.030	0.032	0.034

Cooling method: by convection (method A) Marking: type number Weight: 0.393g

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